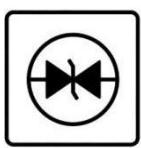




ESD



TVS



TSS



MOV



GDT



PLED

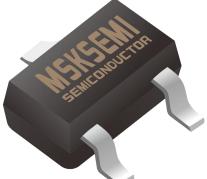
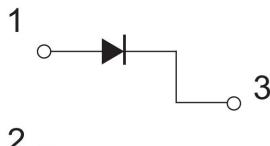
BAS19W/20W/21W

Product specification

FEATURES

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- High Conductance

Reference News

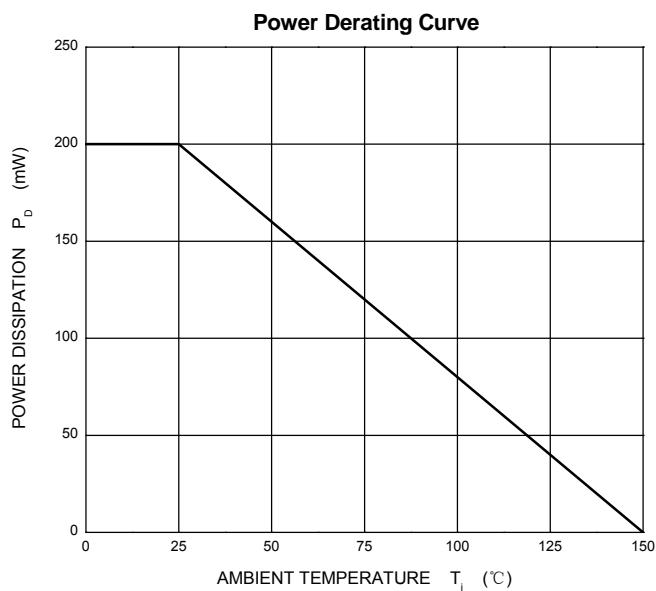
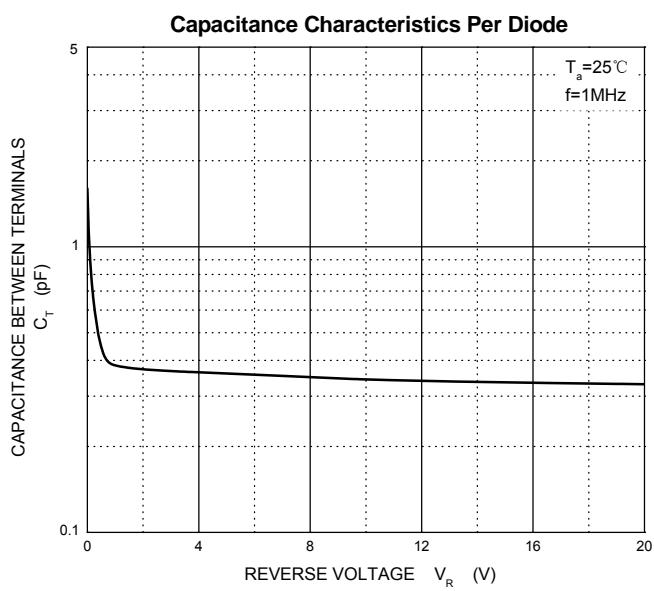
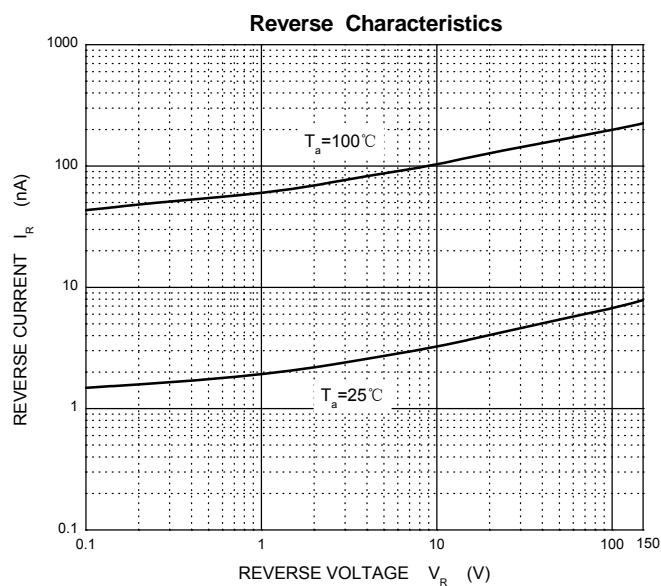
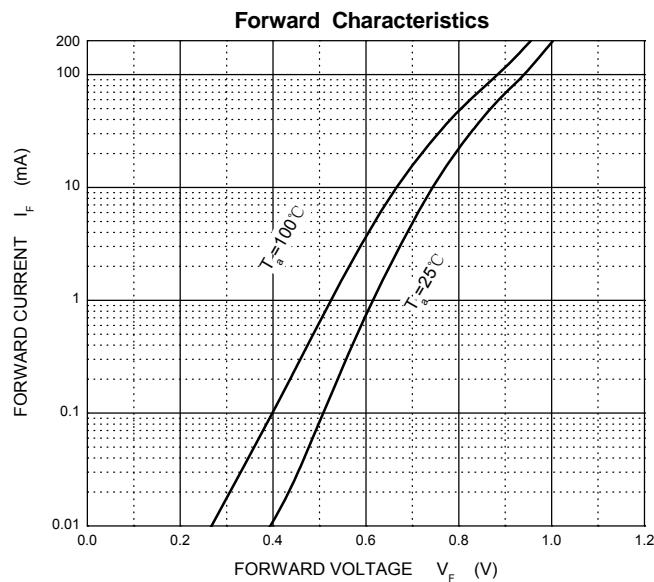
PACKAGE OUTLINE	PIN CONFIGURATION	BAS19W	BAS20W	BAS21W
 SOT-323		KA8 MARKING:KA8	KT2 MARKING:KT2	KT3 MARKING:KT3

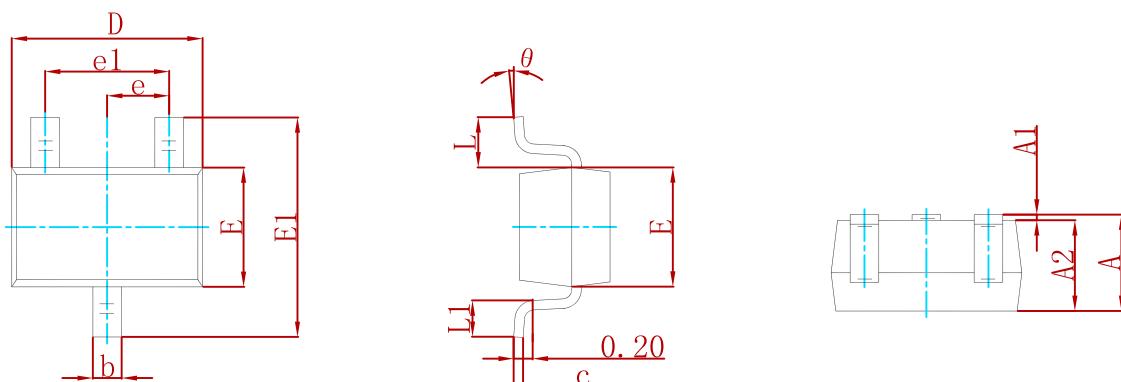
Maximum Ratings @ $T_a=25^\circ C$

Parameter	Symbol	BAS19W	BAS20W	BAS21W	Unit
Peak Repetitive Reverse Voltage	V_{RRM}				
DC Blocking Voltage	V_R	100	150	250	V
Average Rectified Output Current	I_o		200		mA
Non-Repetitive Peak Forward Surge Current @$t=8.3ms$	I_{FSM}		2.5		A
Power Dissipation	P_D		200		mW
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$		625		°C/W
Operation Junction and Storage Temperature Range	T_J, T_{STG}		-55~+150		°C

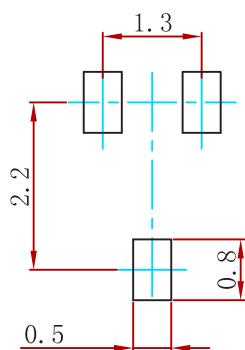
ELECTRICAL CHARACTERISTICS ($T_a=25^\circ C$ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Max	Unit
Reverse breakdown voltage	BAS19W		100		
	BAS20W	$V_{(BR)}$	150		V
	BAS21W		250		
Reverse voltage leakage current	BAS19W	$V_R=100V$			
	BAS20W	$V_R=150V$		0.1	μA
	BAS21W	$V_R=200V$			
Forward voltage	V_F	$I_F=100mA$		1	V
		$I_F=200mA$		1.25	
Diode capacitance	C_D	$V_R=0V, f=1MHz$		5	pF
Reveres recovery time	t_{rr}	$I_F=I_R=30mA, I_{rr}=0.1 \times I_R$		50	ns



PACKAGEMECHANICALDATA


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

Suggested Pad Layout

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAS19W/20W/21W	SOT-323	3000

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